Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**
[List multiple models if applicable.]

HP Pavilion Notebook PC
HP Pavilion Notebook
HP Pavilion Notebook 11

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm M/B</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Battery pack &amp; RTC</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>power cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink,</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td></td>
</tr>
</tbody>
</table>
including liquids, semi-liquids (gel/paste) and toner chambers, and service stations.

Components and waste containing asbestos
Components, parts and materials containing refractory ceramic fibers
Components, parts and materials containing radioactive substances

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw driver</td>
<td>#0</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove rubber foot x 4 screw rubber L / R from D base
2. Remove screw rubber L / R from D base
3. Remove screw M2L5 x 11 from D base
4. Remove C top sub-Assy. from unit
5. Dis-connect K/B membrane, TP FFC, power FFC connector from M/B
6. Remove TP FFC from TP module
7. Remove screw M2L2.5 x 4 on TP support bracket
8. Remove TP support bracket from C top sub-Assy.
9. Remove screw M2L2 x 3 on TP holder bracket
10. Remove TP holder bracket & TP module & TP mylar from C top sub-Assy.
11. Remove power FFC from D/B Pow.
12. Remove screw M2L2.5 x 2 on D/B Pow.
13. Remove D/B Pow. from C top sub-Assy.
14. Dis-connect HDD FFC from M/B
15. Remove HDD
16. Dis-connect speaker connector from M/B
17. Remove screw M2L3 x 2 on speaker box L / R
18. Remove speaker from unit
19. Dis-connect RTC battery connector from M/B
20. Dis-connect battery pack connector from M/B
21. Remove screw M2L3 x 6 on battery pack
22. Remove battery pack from unit
23. Dis-connect D/B FFC connectors from D/B & M/B
24. Remove D/B FFC
25. Remove WWAN antenna cable from WWAN module
26. Remove screw M2L3 x 1 on WWAN module
27. Remove WWAN module from D/B
28. Remove screw M2L3 x 1 on D/B
29. Remove D/B from unit
30. Dis-connect LCD cable connector from M/B
31. Dis-connect DC in cable connector from M/B  
32. Remove screw M2L3 x 1 on DC jack  
33. Remove DC jack from unit  
34. Remove WLAN antenna cable from WLAN module  
35. Remove screw M2L3 x 1 on WLAN module  
36. Remove WLAN module from unit  
37. Remove screw M2L2 x 2 on thermal plate  
38. Remove thermal plate from M/B  
39. Remove screw M2L3 x 4 on M/B  
40. Remove M/B from unit  
41. Remove antenna cable & LCD cable from unit  
42. Remove screw L2.5L4 x 4 on hinge L / R bracket  
43. Remove LCD sub-Assy. from unit  
44. Remove screw mylar L / R on LCD bezel  
45. Remove screw M2L2 x 2 from LCD bezel  
46. Remove LCD bezel from LCD sub-Assy.  
47. Remove screw M2L3 x 4 on LCD ears  
48. Remove LCM from LCD sub-Assy.  
49. Dis-connect LCD cable connector from LCM  
50. Remove screw M2.5L2.5 x 4 & M2L2.5 x 2 on hinge L / R bracket  
51. Remove hinge L / R from LCD sub-Assy.  
52. Dis-connect LCD cable connector from Cam. module  
53. Remove LCD cable from LCD sub-Assy.  
54. Remove Cam. module from LCD sub-Assy.  
55. Remove antenna cable from LCD sub-Assy.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total
3.22 Remove base rubber foot and screw rubber foot -L & -R
3.23 Remove TOP assy..
PSG instructions for this template are available at EL-MF877-01
3.24 Remove power board & TP support bracket & TP module
PSG instructions for this template are available at [EL-MF877-01](#)
PSG instructions for this template are available at EL-MF877-01
3.25 Remove speaker & battery pack & WWAN module & WLAN module
3.26 Remove D/B & D/B FFC & DC in cable & thermal plate & M/B & HDD

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PSG instructions for this template are available at [EL-MF877-01](#).
PSG instructions for this template are available at EL-MF877-01
3.27 Remove Screw Mylar -L & -R and LCD bezel
3.28 Remove Panel
3.29 Remove camera module and hinge -L & -R & LCD cable & antenna cable
PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
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